THE INVENTION CLAIMED IS:

1. A method for fabricating an integrated circuit leadframe, comprising:

forming a leadframe having leads around a die pad, the die pad includes a peripheral die pad rim;

adhering a die to the die pad;

forming a surface configuration in the peripheral die pad rim including an inner raised surface, grooves, and an outer raised surface; the inner raised surface and one of the grooves being between the die and the outer raised surface; and~~:~~

attaching ground bond wire-bonds from the leads to the inner raised surface of the peripheral die pad rim, whereby the surface configuration is for providing clearance space for the ground bond wire-bonds from other wire-bonds.

2. The method of claim 1 wherein forming the surface configuration includes forming depressed separation structures.

3. The method of claim 1 wherein forming the surface configuration includes forming a sequence of discrete, alternately staggered grooves.

4. The method of claim 1 wherein forming the surface configuration includes forming X-shaped grooves for forming a discrete, alternately staggered surface configuration in the die pad.

5. The method of claim 1 wherein forming the surface configuration includes forming U-shaped grooves for forming a discrete, alternately staggered surface configuration in the die pad.

7. The method of claim 6 wherein forming the surface configuration includes forming depressed separation structures.

8. The method of claim 6 wherein forming the surface configuration includes forming a sequence of discrete~~;~~, alternately staggered grooves.

9. The method of claim 6 wherein forming the surface configuration includes forming X-shaped grooves for forming a discrete, alternately staggered surface configuration in the die pad.

10. The method of claim 6 wherein forming the surface configuration includes forming U-shaped grooves for forming a discrete, alternately staggered surface configuration in the die pad.

11. A leadframe for an integrated circuit, comprising:

a die pad having;

a peripheral die pad rim on the die pad, and~~;~~

a surface configuration having an inner raised surface, grooves, and an outer raised surface on the peripheral die pad rim;

a die mounted on the die pad, the inner raised surface and one of the grooves being between the die and the outer raised surface;

leads around the peripheral die pad rim; and

ground bond wire-bonds attached from the leads to the inner raised surface of the peripheral die pad rim, whereby the surface configuration is for providing clearance space for the ground bond wire-bonds from other wire-bonds.

12. The leadframe of claim 11 wherein the surface configuration includes depressed separation structures.

13. The leadframe of claim 11 wherein the surface configuration includes a sequence of discrete, alternately staggered grooves.